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5-8-02  
McAllish

Docket No.: 50090-466

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of :  
Hiroshi HORIBE :  
Serial No.: Group Art Unit:  
Filed: January 18, 2002 : Examiner:

For: SEMICONDUCTOR DEVICE AND WIRE BONDING APPARATUS



**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

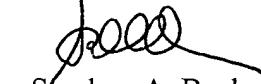
DESI AVAILBLE U/R

Serial No.:

Each non-English reference is accompanied by an English Abstract.

Respectfully submitted,

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